

Ceramic PCB manufacturing capabilities

Lexington Europe GmbH
www.lexington-pcb.com

Items		Thick Film	DBC
Max Layer Count		10layer	2layer
Minimum Board Thickness	1L	0.25mm	0.3mm
	2L	0.28mm	0.4mm
	4L	0.34mm	N/A
	6L	0.46mm	N/A
	8L	0.81mm	N/A
	10L	1.05mm	N/A
Max Board Thickness		6mm	2.4mm
Max Board Dimension		200*200mm	138*178mm
Min Board Dimension		10*10mm	10*10mm
Max Conductor thickness		13um	0.3mm
Minimum conductor thickness		5um	0.1mm
Min Trace Width/Space		0.25/0.25mm	0.25/0.25mm
Min Hole Diameter		0.1mm	0.1mm
Min Hole Spacing		NPTH: 0.3mm PTH: 0.5mm	NPTH: 0.3mm PTH: 0.5mm
Max Aspect Ratio		8:1	8:1
Min Solder PAD Dia		0.25mm	0.25mm
Min PAD Ring (Single Side)		0.15mm	0.15mm
PTH Wall Thickness		10um	N/A
PTH Dia Tolerance		± 0.10mm	± 0.10mm
NPTH Dia Tolerance		± 0.050mm	± 0.050mm
Hole Position Deviation		± 0.10mm	± 0.10mm
Outline Tolerance		Laser: +0.20mm/-0.05mm	Laser: +0.20mm/-0.05mm
Outline Tolerance		Die Punch: +0.25mm/-0.2mm	Die Punch: +0.25mm/-0.2mm
Min Soldermask Bridge		0.3mm	0.3mm
Min BAG PAD Margin		0.3mm	0.3mm
Thermal Conductivity (W/m.K or W/m.C)		Al2O3: 24; AlN/BeO: min.170	Al2O3: 24; AlN/BeO: min.170
Dielectric Strength		Min. 15 KV/mm	Min. 15 KV/mm
Wrap & Twist		<=3%	<=3%
Surface finish		AgPd, AuPd	Ni plating, ENIG
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